Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.052 X .052”**

**.060”**

**.060”**

**For Zener operation, Cathode must be operated positive with respect to Anode.**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .052” X .052”**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .060” X .060” DATE: 11/10/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 1N5352B**

**DG 10.1.2**

#### Rev B, 7/19/02